



May 19, 2023

For Immediate Release

Company name: Hibiya Engineering, Ltd.
Representative: Nagahiro Kuroda, President and CEO
(Tokyo Stock Exchange, Prime Market Stock code: 1982)
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Notice of Dividends of Surplus

Hibiya Engineering, Ltd. (the “Company”) announces that a meeting of the Board of Directors held on May 19, 2023 resolved to pay dividends of surplus with March 31, 2023 as the record date, as shown below.

The Company will submit this matter to the 58th Ordinary General Meeting of Shareholders to be held on June 23, 2023.

1. Details of dividends

	Amount determined (Period ended March 31, 2023)	Immediately preceding dividend forecast (Announced on May 11, 2023)	Results of previous fiscal year (Period ended March 31, 2022)
Record date	March 31, 2023	Same as left	March 31, 2022
Dividends per share	43 yen	43 yen	42 yen
Total dividends	991 million yen	–	992 million yen
Effective date	June 26, 2023	–	June 24, 2022
Source of dividends	Retained earnings	–	Retained earnings

2. Reason

The Company considers the return of earnings to shareholders as the most important management issue. The Company’s basic policy is to pay stable and continuous dividends while adopting a long-term perspective and taking into consideration factors such as consolidated performance and financial position.

Based on the above policy, the Company decided to pay a dividend of 43 yen per share as the year-end dividend for the fiscal year ended March 31, 2023. As a result, the annual dividend per share will be 85 yen per share, including the interim dividend of 42 yen per share which has already been paid.

(Reference) Details of annual dividend

Record date	Dividends per share		
	Interim	Year-end	Annual
Actual dividends FY3/23	42 yen	43 yen	85 yen
Actual dividends FY3/22	40 yen	42 yen	82 yen